

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-083877

(43)Date of publication of application : 26.03.1996

(51)Int.Cl. H01L 23/50  
H01L 23/28

(21)Application number : 07-022243

(71)Applicant : SONY CORP

(22)Date of filing : 17.01.1995

(72)Inventor : NAKANO SEIJI  
MOGAMI KEIICHI

(30)Priority

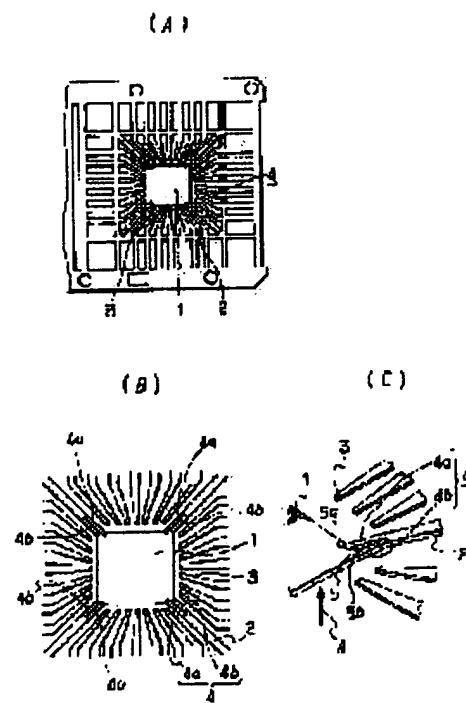
Priority number : 06182917 Priority date : 12.07.1994 Priority country : JP

(54) LEAD FRAME

(57)Abstract:

PURPOSE: To prevent deformation or open circuit of a wire, package crack, and the like due to variation in the position or direction, especially floating, of a die pad or a semiconductor element supported thereon caused by the pressure of resin at the time of resin sealing by enhancing the mechanical strength at the depress part of a support lead.

CONSTITUTION: In a lead frame where the root part of a lead 2 supporting a die pad 1 which supports a semiconductor element is depressed, the depressed part 4 of the support lead 2 is split into a plurality of subsections 4a, 4b. One subsection 4a is set longer than the other subsection 4b wherein the subsections 4a, 4b and the support lead 2 of the die pad 1 substantially define a triangle, when the depressed part is viewed from the side, thus providing a reinforcing part.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the

examiner's decision of rejection or application

converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of  
rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office